

## N-CHANNEL 60V - 0.020 Ω - 28A IPAK/DPAK STripFET™ II POWER MOSFET

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	ID
STD30NF06	60 V	<0.028 Ω	28 A

- TYPICAL  $R_{DS}(on) = 0.020\Omega$
- EXCEPTIONAL dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- THROUGH-HOLE IPAK (TO-251) POWER PACKAGE IN TUBE (SUFFIX "-1")
- SURFACE-MOUNTING DPAK (TO-252) POWER PACKAGE IN TAPE & REEL (SUFFIX "T4")

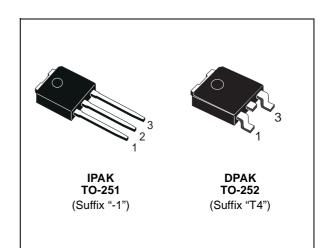
#### DESCRIPTION

This Power MOSFET is the latest development of STMicroelectronis unique "Single Feature Size<sup>TM</sup>" stripbased process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

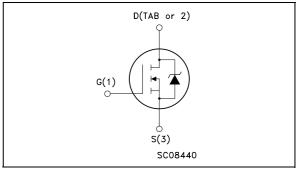
#### APPLICATIONS

- HIGH CURRENT, HIGH SWITCHING SPEED
- MOTOR CONTROL , AUDIO AMPLIFIERS
- SOLENOID AND RELAY DRIVERS
- DC-DC & DC-AC CONVERTERS

**ABSOLUTE MAXIMUM RATINGS** 



#### INTERNAL SCHEMATIC DIAGRAM



Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage ( $V_{GS} = 0$ )	60	V
Vdgr	Drain-gate Voltage ( $R_{GS}$ = 20 k $\Omega$ )	60	V
V <sub>GS</sub>	Gate- source Voltage	± 20	V
ID	Drain Current (continuous) at $T_C = 25^{\circ}C$	28	Α
ID	Drain Current (continuous) at T <sub>C</sub> = 100°C	20	A
I <sub>DM</sub> (•)	Drain Current (pulsed)	112	A
P <sub>tot</sub>	Total Dissipation at $T_C = 25^{\circ}C$	70	W
	Derating Factor	0.47	W/°C
dv/dt (1)	Peak Diode Recovery voltage slope	10	V/ns
E <sub>AS</sub> (2)	Single Pulse Avalanche Energy	230	mJ
T <sub>stg</sub> Storage Temperature		-55 to 175	°C
Tj	Max. Operating Junction Temperature	-55 10 175	
Pulse width	limited by safe operating area.	(1) $I_{SD} \le 28A$ , di/dt $\le 300A/\mu s$ , $V_{DD} \le V_{(BR)DSS}$ , $T_j \le$ (2) Starting T: = 25 °C, $I_D = 15A$ , $V_{DD} = 30V$	T <sub>JMAX</sub>

(2) Starting  $T_j = 25 \text{ °C}$ ,  $I_D = 15A$ ,  $V_{DD} = 30V$ 

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#### THERMAL DATA

Rthj-case Rthj-amb Tl	Thermal Resistance Junction-case Thermal Resistance Junction-ambient Maximum Lead Temperature For Soldering Purpose	Max Max	2.14 100 275	°C/W °C/W °C
1	Maximum Leau Temperature For Soluening Fulpose		215	C

### **ELECTRICAL CHARACTERISTICS** (T<sub>case</sub> = 25 °C unless otherwise specified)

#### OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	$V_{DS}$ = Max Rating $V_{DS}$ = Max Rating T <sub>C</sub> = 100°C			1 10	μΑ μΑ
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 20 V			±100	nA

#### ON (\*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I <sub>D</sub> = 250 μA	2		4	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 15 A		0.020	0.028	Ω

#### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	V <sub>DS</sub> = 15 V I <sub>D</sub> = 15 A		40		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V <sub>DS</sub> = 25V, f = 1 MHz, V <sub>GS</sub> = 0		1750 220 70		pF pF pF

#### ELECTRICAL CHARACTERISTICS (continued)

#### SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Delay Time Rise Time			20 100		ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V <sub>DD</sub> = 48V I <sub>D</sub> = 38A V <sub>GS</sub> = 10V		43 9.5 15	58	nC nC nC

#### SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(off)</sub> t <sub>f</sub>	Turn-off Delay Time Fall Time			50 20		ns ns

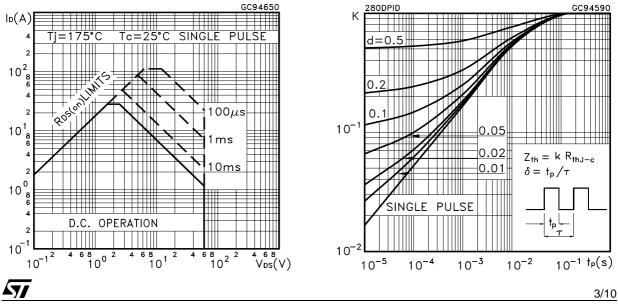
#### SOURCE DRAIN DIODE

Symbol	Parameter	Test Co	Test Conditions		Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (●)	Source-drain Current Source-drain Current (pulsed)					28 112	A A
V <sub>SD</sub> (*)	Forward On Voltage	I <sub>SD</sub> = 28 A	$V_{GS} = 0$			1.5	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 28 \text{ A}$ $V_{DD} = 30 \text{ V}$ (see test circu	di/dt = 100A/µs T <sub>j</sub> = 150°C it, Figure 5)		95 260 5.5		ns μC Α

(\*)Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5 %.

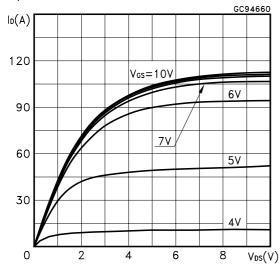
(•)Pulse width limited by safe operating area.

#### Safe Operating Area

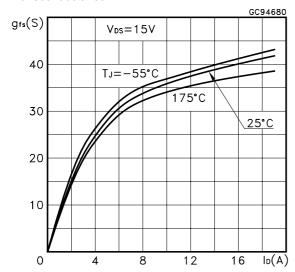


Thermal Impedance

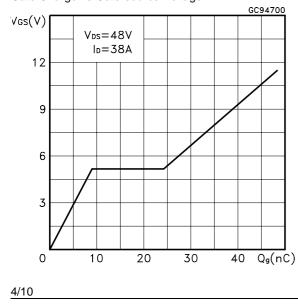
#### **Output Characteristics**



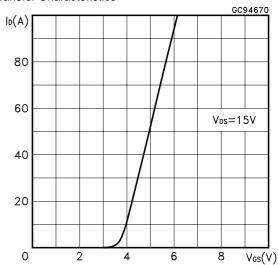
Transconductance

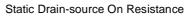


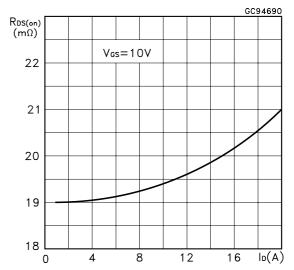




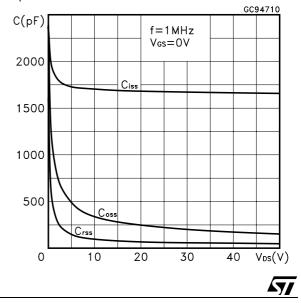


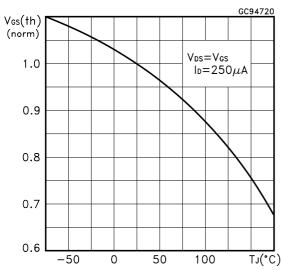






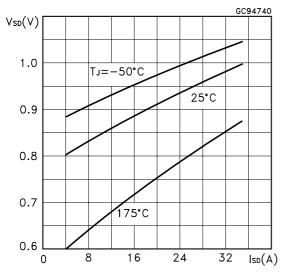
Capacitance Variations



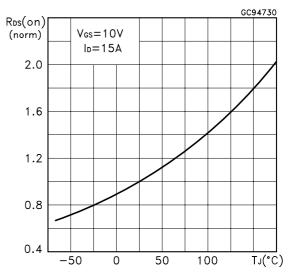


Normalized Gate Threshold Voltage vs Temperature

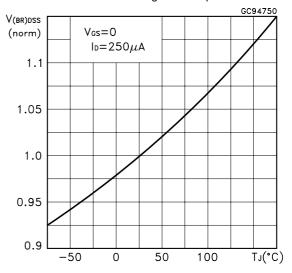
Source-drain Diode Forward Characteristics



Normalized on Resistance vs Temperature



Normalized Breakdown Voltage vs Temperature



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Fig. 1: Unclamped Inductive Load Test Circuit

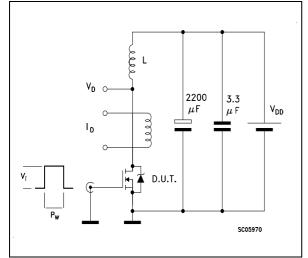
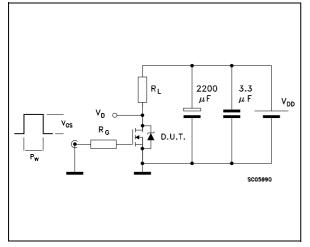
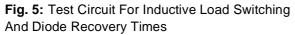
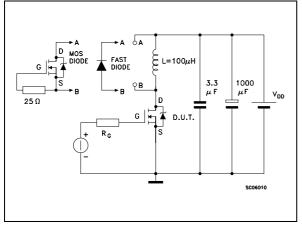


Fig. 3: Switching Times Test Circuits For Resistive Load







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#### Fig. 2: Unclamped Inductive Waveform

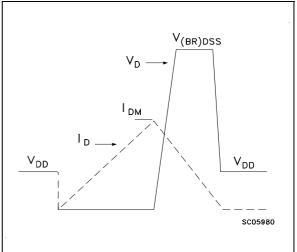
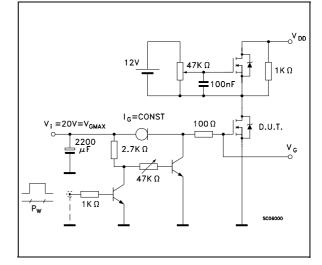


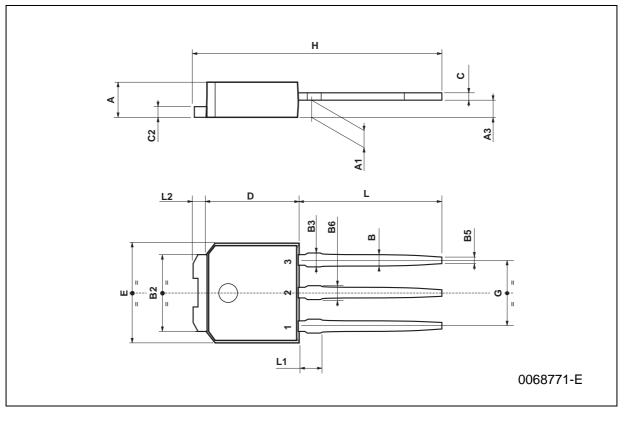
Fig. 4: Gate Charge test Circuit





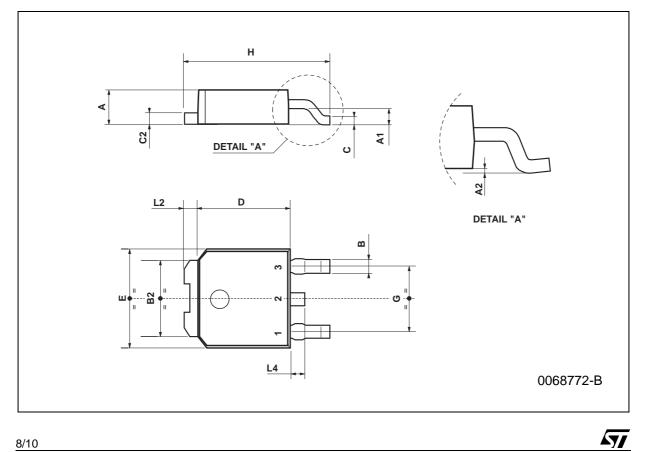
DIM.		mm			inch	
DINI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A3	0.7		1.3	0.027		0.051
В	0.64		0.9	0.025		0.031
B2	5.2		5.4	0.204		0.212
B3			0.85			0.033
B5		0.3			0.012	
B6			0.95			0.037
С	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
Е	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
Н	15.9		16.3	0.626		0.641
L	9		9.4	0.354		0.370
L1	0.8		1.2	0.031		0.047
L2		0.8	1		0.031	0.039

## TO-251 (IPAK) MECHANICAL DATA

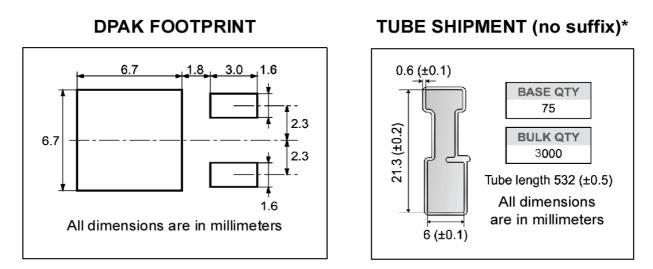


DIM.		mm		inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.009
В	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
С	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
н	9.35		10.1	0.368		0.397
L2		0.8			0.031	
L4	0.6		1	0.023		0.039

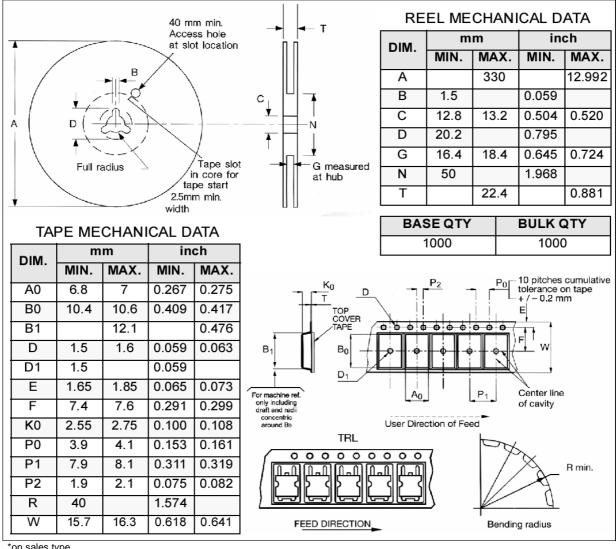








## TAPE AND REEL SHIPMENT (suffix "T4")\*



\*on sales type

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